

2 OUTPUT PCIE GEN1/2 SYNTHESIZER

IDT5V41285

Recommended Applications

2 output synthesizer for PCIe Gen1/2 and Ethernet

General Description

The IDT5V41285 is a PCIe Gen2 compliant clock generator. The device has 2 differential HCSL outputs. The output frequency is selectable via select pins.

Output Features

2 - Non-spread 0.7V current mode differential HCSL output pairs

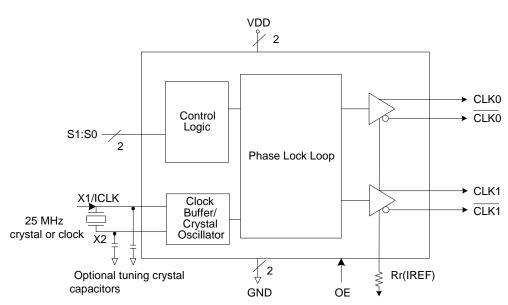
Features/Benefits

- 16-pin TSSOP and VFQFPN packages; small board footprint
- Outputs can be terminated to LVDS; can drive a wider variety of devices
- OE control pin; greater system power management
- Industrial temperature range available; supports demanding embedded applications
- For PCle Gen3 applications, see the IDT5V41315

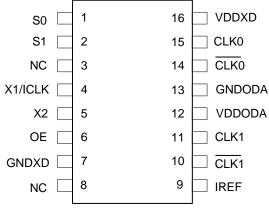
Key Specifications

- Cycle-to-cycle jitter: 80ps
- Output-to-output skew <50 ps
- PCle Gen2 phase jitter <3.0ps RMS
- Low phase noise: 12kHz to 20MHz <6ps

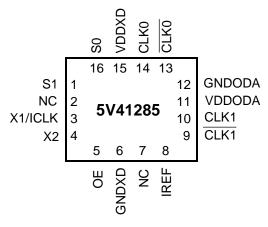
Block Diagram



Pin Assignment



16-pin (173 mil) TSSOP



16-pin VFQFPN

Output Select Table 1 (MHz)

S1	S0	CLK(1:0), CLK(1:0)
0	0	25M
0	1	100M
1	0	125M
1	1	200M

Pin Descriptions

VFQFP	TSSOP	Pin	Pin	Pin Description
Pin	Pin	Name	Type	
Number	Number			
16	1	S0	Input	Select pin 0. See Output Select Table 1. Internal pull-up resistor.
1	2	S1	Input	Select pin 1. See Output Select Table 1. Internal pull-up resistor.
2	3	NC	_	No connect.
3	4	X1/ICLK	Input	Crystal or clock input. Connect to a 25 MHz crystal or single ended clock.
4	5	X2	Output	Crystal connection. Leave unconnected for clock input.
5	6	OE	Input	Output enable. Tri-states outputs and device is not shut down. Internal pull-up resistor.
6	7	GNDXD	Power	Connect to ground.
7	8	NC	_	No connect.
8	9	IREF	Output	Precision resistor attached to this pin is connected to the internal current reference.
9	10	CLK1	Output	HCSL complementary clock output 1.
10	11	CLK1	Output	HCSL true clock output 1.
11	12	VDDODA	Power	Connect to voltage supply +3.3 V for output driver and analog circuits
12	13	GNDODA	Power	Connect to ground.
13	14	CLK0	Output	HCSL complementary clock output 0.
14	15	CLK0	Output	HCSL true clock output 0.
15	16	VDDXD	Power	Connect to voltage supply +3.3 V for crystal oscillator and digital circuit.

Applications Information

External Components

A minimum number of external components are required for proper operation.

Decoupling Capacitors

Decoupling capacitors of 0.01 μF should be connected between each VDD pin and the ground plane, as close to the VDD pin as possible. Do not share ground vias between components. Route power from power source through the capacitor pad and then into ICS pin.

Crystal

A 25 MHz fundamental mode parallel resonant crystal should be used. This crystal must have less than 300 ppm of error across temperature in order for the IDT5V41285 to meet PCI Express specifications.

Crystal Capacitors

Crystal capacitors are connected from pins X1 to ground and X2 to ground to optimize the accuracy of the output frequency.

C_I = Crystal's load capacitance in pF

Crystal Capacitors (pF) = $(C_1 - 8) * 2$

For example, for a crystal with a 16 pF load cap, each external crystal cap would be 16 pF. (16-8)*2=16.

Current Source (Iref) Reference Resistor - RR

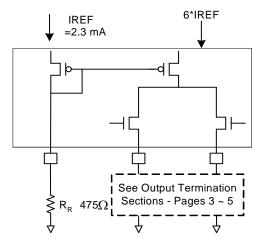
If board target trace impedance (Z) is 50Ω , then $R_R=475\Omega$ (1%), providing IREF of 2.32 mA. The output current (I_{OH}) is equal to 6*IREF.

Output Termination

The PCI-Express differential clock outputs of the IDT5V41285 are open source drivers and require an external series resistor and a resistor to ground. These resistor values and their allowable locations are shown in detail in the **PCI-Express Layout Guidelines** section.

The IDT5V41285 can also be configured for LVDS compatible voltage levels. See the LVDS Compatible Layout Guidelines section.

Output Structures



General PCB Layout Recommendations

For optimum device performance and lowest output phase noise, the following guidelines should be observed.

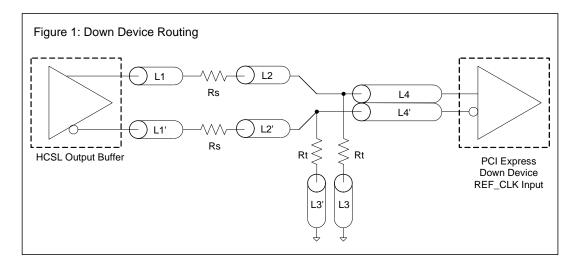
- 1. Each $0.01\mu F$ decoupling capacitor should be mounted on the component side of the board as close to the VDD pin as possible.
- 2. No vias should be used between decoupling capacitor and VDD pin.
- 3. The PCB trace to VDD pin should be kept as short as possible, as should the PCB trace to the ground via. Distance of the ferrite bead and bulk decoupling from the device is less critical.
- 4. An optimum layout is one with all components on the same side of the board, minimizing vias through other signal layers (any ferrite beads and bulk decoupling capacitors can be mounted on the back). Other signal traces should be routed away from the IDT5V41285. This includes signal traces just underneath the device, or on layers adjacent to the ground plane layer used by the device.

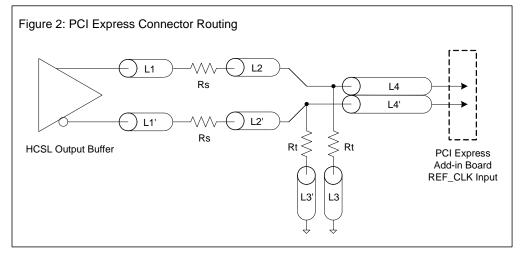
Layout Guidelines

SRC Reference Clock						
Common Recommendations for Differential Routing	Dimension or Value	Unit	Figure			
L1 length, route as non-coupled 50ohm trace	0.5 max	inch	1			
L2 length, route as non-coupled 50ohm trace	0.2 max	inch	1			
L3 length, route as non-coupled 50ohm trace	0.2 max	inch	1			
Rs	33	ohm	1			
Rt	49.9	ohm	1			

Down Device Differential Routing			
L4 length, route as coupled microstrip 100ohm differential trace	2 min to 16 max	inch	1
L4 length, route as coupled stripline 100ohm differential trace	1.8 min to 14.4 max	inch	1

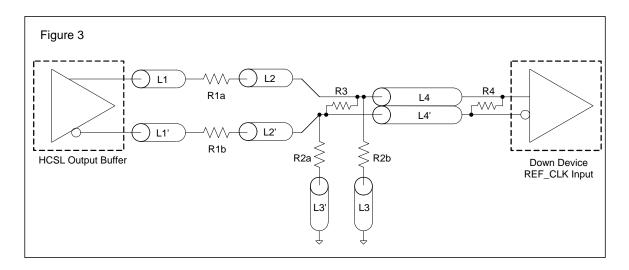
Differential Routing to PCI Express Connector			
L4 length, route as coupled microstrip 100ohm differential trace	0.25 to 14 max	inch	2
L4 length, route as coupled stripline 100ohm differential trace	0.225 min to 12.6 max	inch	2



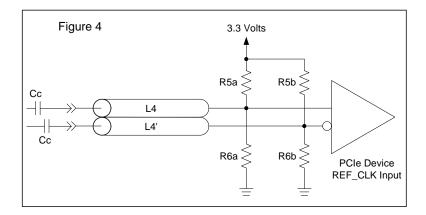


	Alternative Termination for LVDS and other Common Differential Signals (figure 3)									
Vdiff Vp-p Vcm R1 R2 R3 R4 Note							Note			
0.45 v	0.22v	1.08	33	150	100	100				
0.58	0.28	0.6	33	78.7	137	100				
0.80	0.40	0.6	33	78.7	none	100	ICS874003i-02 input compatible			
0.60	0.3	1.2	33	174	140	100	Standard LVDS			

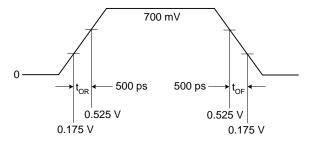
R1a = R1b = R1R2a = R2b = R2



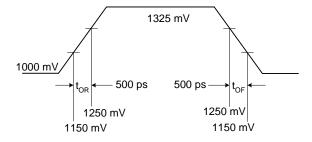
Cable Connec	Cable Connected AC Coupled Application (figure 4)					
Component	Value	Note				
R5a, R5b	8.2K 5%					
R6a, R6b	1K 5%					
Cc	0.1 μF					
Vcm	0.350 volts					



Typical PCI-Express (HCSL) Waveform



Typical LVDS Waveform



Absolute Maximum Ratings

Stresses above the ratings listed below can cause permanent damage to the IDT5V41285. These ratings are stress ratings only. Functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods can affect product reliability. Electrical parameters are guaranteed only over the recommended operating temperature range.

Item	Rating
Supply Voltage, VDDXD, VDDODA	4.6 V
All Inputs and Outputs	-0.5 V to VDD+0.5 V
Ambient Operating Temperature (commercial)	0 to +70°C
Ambient Operating Temperature (industrial)	-40 to +85°C
Storage Temperature	-65 to +150°C
Junction Temperature	125°C
Soldering Temperature	260°C
ESD Protection (Input)	2000 V min. (HBM)

DC Electrical Characteristics

Unless stated otherwise, VDD = 3.3 V ±5%, Ambient Temperature -40 to +85°C

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Supply Voltage	V		3.135	3.3	3.465	V
Input High Voltage ¹	V _{IH}	S0, S1, OE, ICLK	2.2		VDD +0.3	V
Input Low Voltage ¹	V_{IL}	S0, S1, OE, ICLK	VSS-0.3		0.8	V
Input Leakage Current ²	I _{IL}	0 < Vin < VDD	-5		5	μΑ
Operating Supply Current	I _{DD}	$R_S=33\Omega$, $R_P=50\Omega$, $C_L=2$ pF		63	85	mA
@100 MHz	I _{DDOE}	OE =Low		42	50	mA
Input Capacitance	C _{IN}	Input pin capacitance			7	pF
Output Capacitance	C _{OUT}	Output pin capacitance			6	pF
X1, X2 Capacitance	C _{INX}				5	pF
Pin Inductance	L _{PIN}				5	nΗ
Output Impedance	Z _O	CLK outputs	3.0			kΩ
Pull-up Resistor	R _{PU}	S0, S1, OE		100		kΩ

- 1. Single edge is monotonic when transitioning through region.
- 2. Inputs with pull-ups/-downs are not included.

AC Electrical Characteristics - CLK0/CLK1, CLK0/CLK1

Unless stated otherwise, VDD=3.3 V ±5%, Ambient Temperature -40 to +85°C

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Input Frequency				25		MHz
Output Frequency		HCSL termination	25		200	MHz
		LVDS termination	25		100	MHz
Output High Voltage ^{1,2}	V _{OH}	HCSL			850	mV
Output Low Voltage ^{1,2}	V _{OL}	HCSL	-150			mV
Crossing Point Voltage ^{1,2}		Absolute	250		550	mV
Crossing Point Voltage ^{1,2,4}		Variation over all edges			140	mV
Jitter, Cycle-to-Cycle ^{1,3}					80	ps
Frequency Synthesis Error		All outputs		0		ppm
Rise Time ^{1,2}	t _{OR}	From 0.175 V to 0.525 V	175		700	ps
Fall Time ^{1,2}	t _{OF}	From 0.525 V to 0.175 V	175		700	ps
Rise/Fall Time Variation ^{1,2}					125	ps
Output to Output Skew					50	ps
Duty Cycle ^{1,3}			45		55	%
Output Enable Time ⁵		All outputs		50	100	ns
Output Disable Time ⁵		All outputs		50	100	ns
Stabilization Time	t _{STABLE}	From power-up VDD=3.3 V			1.8	ms

- Note 1: Test setup is $R_S=33\Omega$, $R_P=50\Omega$ with $C_I=2$ pF, $R_I=475\Omega$ (1%).
- Note 2: Measurement taken from a single-ended waveform.
- Note 3: Measurement taken from a differential waveform.
- Note 4: Measured at the crossing point where instantaneous voltages of both CLK and CLK are equal.
- Note 5: CLK pins are tri-stated when OE is low asserted. CLK is driven differential when OE is high.

Electrical Characteristics - Differential Phase Jitter

Parameter	Symbol	Conditions		Тур	Max	Units	Notes
	t _{jphasePLL}	PCle Gen1		32	86	ps (p-p)	1,2
Jitter, Phase	t _{jphaseLO}	PCle Gen2, 10 kHz < f < 1.5 MHz		0.8	3	ps (RMS)	1,2
	t _{jphaseHIGH}	PCIe Gen2, 1.5 MHz < f < Nyquist (50 MHz)		2.3	3.1	ps (RMS)	1,2

- Note 1. Guaranteed by design and characterization, not 100% tested in production.
- Note 2. See http://www.pcisig.com for complete specs.

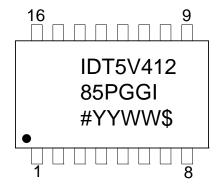
Thermal Characteristics (16-TSSOP)

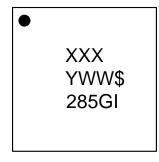
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Thermal Resistance Junction to	$\theta_{\sf JA}$	Still air		78		°C/W
Ambient	$\theta_{\sf JA}$	1 m/s air flow		70		°C/W
	$\theta_{\sf JA}$	3 m/s air flow		68		°C/W
Thermal Resistance Junction to Case	$\theta_{\sf JC}$			37		°C/W

Thermal Characteristics (16-VFQFPN)

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Thermal Resistance Junction to	$\theta_{\sf JA}$	Still air		63.2		°C/W
Ambient	$\theta_{\sf JA}$	1 m/s air flow		55.9		°C/W
	θ_{JA}	3 m/s air flow		51.4		°C/W
Thermal Resistance Junction to Case	θ JC			65.8		°C/W

Marking Diagrams





Notes:

- 1. Line 1 and 2: IDT part number.
- 2. Line 3: # Die revision; YYWW Date code; \$–Assembly location.
- 3. "G" after the two-letter package code designates RoHS compliant package.
- 4. "I" at the end of part number indicates industrial temperature range.
- 5. Bottom marking: country of origin if not USA (TSSOP only).

REVISIONS

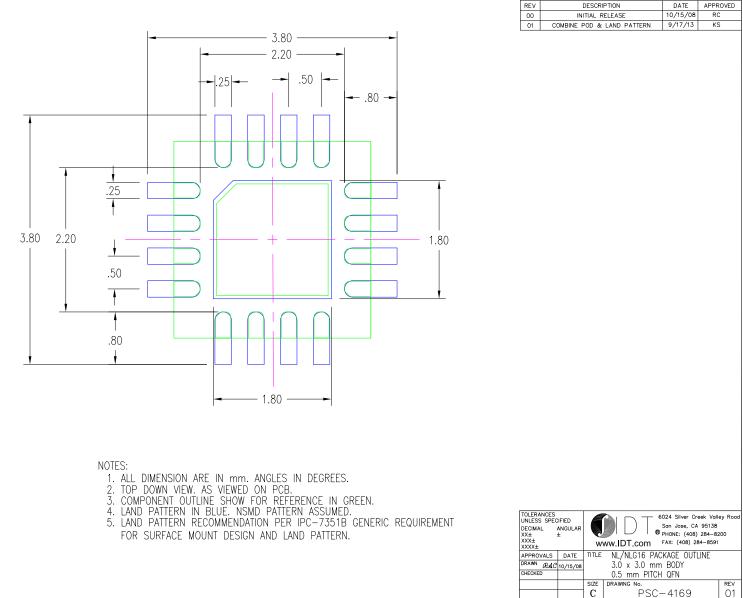
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Package Outline and Dimensions (3 x 3mm 16-VFQFPN), cont.

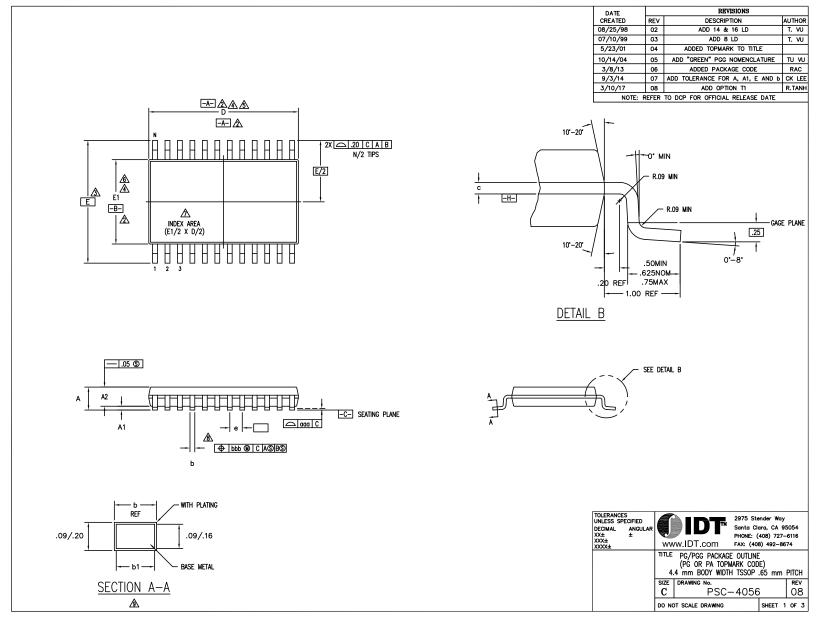
REVISIONS REV DESCRIPTION DATE APPROVED 00 INITIAL RELEASE 10/15/08 RC 9/17/13 KS COMBINE POD & LAND PATTERN

DO NOT SCALE DRAWING

SHEET 2 OF 2



Package Outline and Dimensions (4.4 mm body, 16-TSSOP)



REVISIONS AUTHOR CREATED REV DESCRIPTION 08/25/98 02 ADD 14 & 16 LD T. VU 07/10/99 03 ADD 8 LD T. VU 5/23/01 04 ADDED TOPMARK TO TITLE 10/14/04 05 ADD "GREEN" PGG NOMENCLATURE TU VU 3/8/13 06 ADDED PACKAGE CODE RAC 9/3/14 07 ADD TOLERANCE FOR A, A1, E AND b CK LEE R.TANH 3/10/17 08 ADD OPTION T1 NOTE: REFER TO DCP FOR OFFICIAL RELEASE DATE

Package Outline and Dimensions (4.4 mm body, 16-TSSOP), cont.

IDT5V41285 2 OUTPUT PCIE GEN1/2 SYNTHESIZER

		PG/P	GG8			PG/P	GG14			PG/P	3G16			PG/P	GG20			PG/P	GG24			PG/P	3G28	
S Y M	JEDE	C VARIAT	ION	ΣĽ	JEDE	C VARIAT	ION	N	JEDE	C VARIAT	ION	זכ	JEDE	C VARIAT	ION	N	JEDE	C VARIAT	ION	ZC	JEDE	C VARIAT	ION	Ŋ
B		AA		ĮĮ		AB-1		ΙĬΙ		AB		Ĭ		AC		Ī		AD		Ĭ		AE		ΙĬΙ
Ľ	MIN	NOM	MAX	E	MIN	NOM	MAX	E	MIN	NOM	MAX	E	MIN	NOM	MAX	Ε	MIN	NOM	MAX	E	MIN	NOM	MAX	E
Α	.85	1.10	1.20		.85	1.10	1.20		.85	1.10	1.20		.85	1.10	1.20		.85	1.10	1.20		.85	1.10	1.20	
A1	.05	.10	.15		.05	.10	.15		.05	.10	.15		.05	.10	.15		.05	.10	.15		.05	.10	.15	
A2	.80	1.00	1.05		.80	1.00	1.05		.80	1.00	1.05		.80	1.00	1.05		.80	1.00	1.05		.80	1.00	1.05	
D	2.90	3.00	3.10	4,5	4.90	5.00	5.10	4,5	4.90	5.00	5.10	4,5	6.40	6.50	6.60	4,5	7.70	7.80	7.90	4,5	9.60	9.70	9.80	4,5
Ε	6.20	6.40	6.60	3	6.20	6.40	6.60	3	6.20	6.40	6.60	3	6.20	6.40	6.60	3	6.20	6.40	6.60	3	6.20	6.40	6.60	3
E1	4.30	4.40	4.50	4,6	4.30	4.40	4.50	4,6	4.30	4.40	4.50	4,6	4.30	4.40	4.50	4,6	4.30	4.40	4.50	4,6	4.30	4.40	4.50	4,6
е		.65 BSC				.65 BSC				.65 BSC			.65 BSC			.65 BSC					.65 BSC			
Ь	.19	.25	.30		.19	.25	.30		.19	.25	.30		.19	.25	.30		.19	.25	.30		.19	.25	.30	
b1	.19	.22	.25		.19	.22	.25		.19	.22	.25		.19	.22	.25		.19	.22	.25		.19	.22	.25	
aaa	-	_	.10		_	_	.10		ı	-	.10		_	ı	.10		_	_	.10		_	ı	.10	
bbb	-	_	.10		_	_	.10		ı	-	.10		_	ı	.10		_	_	.10		_	-	.10	
N		8				14				16				20				24				28		

NOTES:

1 ALL DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5M-1994

△ DATUMS —A— AND —B— TO BE DETERMINED AT DATUM PLANE —H—

DIMENSION E TO BE DETERMINED AT SEATING PLANE -C-

DIMENSIONS D AND E1 ARE TO BE DETERMINED AT DATUM PLANE -H-

DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED .15 mm PER SIDE

DIMENSION E1 DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSIONS. INTERLEAD FLASH OR PROTRUSIONS SHALL NOT EXCEED .25 mm PER SIDE

DETAIL OF PIN 1 IDENTIFIER IS OPTIONAL BUT MUST BE LOCATED WITHIN THE ZONE INDICATED

LEAD WIDTH DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION IS .08 mm IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT

THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN .10 AND .25 mm FROM THE LEAD TIP

10 ALL DIMENSIONS ARE IN MILLIMETERS

11

THIS OUTLINE CONFORMS TO JEDEC PUBLICATION 95 REGISTRATION MO-153, VARIATION AA, AB-1, AB, AC, AD & AE

		OPTION T1									
		PGG14	4T1								
Ø¥₩□⊔	JEDE	l N									
B		AB-1		N E							
-	MIN	NOM	MAX] È							
Α	.90	1.10	1.20								
A1	.05	.10	.15								
A2	.80	1.00	1.05								
D	4.90	5.00	5.10	4,5							
Ε	6.20	6.40	6.60	3							
E1	4.30	4.40	4.50	4,6							
е		.65 BSC	-								
b	.19	.25	.30								
b1	.19	.22	.25								
С	.09	-	.20								
aaa	-	-	.10								
bbb	-	-	.10								
N											

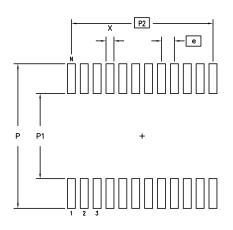
TOLERANCES UNLESS SPECIFIED DECIMAL ANGULAR XX± ± XXX± XXXX±	IDT ™ www.IDT.com	2975 Stender Way Santa Clara, CA 95054 PHONE: (408) 727-6116 FAX: (408) 492-8674					
	TITLE PG/PGG PACKAGE OUTLINE (PG OR PA TOPMARK CODE) 4.4 mm BODY WIDTH TSSOP .65 mm PITCH						
	SIZE DRAWING No. C PSC-	-4056 REV					
	DO NOT SCALE DRAWING	SHEET 2 OF 3					

Package Outline and Dimensions (4.4 mm body, 16-TSSOP), cont.

MAY 8, 2017

REVISIONS DATE CREATED AUTHOR T. VU T. VU REV 02 DESCRIPTION 08/25/98 ADD 14 & 16 LD 07/10/99 03 ADD 8 LD 5/23/01 ADDED TOPMARK TO TITLE 04 TU VU RAC 10/14/04 ADD "GREEN" PGG NOMENCLATURE 05 3/8/13 06 ADDED PACKAGE CODE 9/3/14 07 ADD TOLERANCE FOR A, A1, E AND b CK LEE 3/10/17 08 ADD OPTION T1 R.TANH NOTE: REFER TO DCP FOR OFFICIAL RELEASE DATE

LAND PATTERN DIMENSIONS



	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
Р	7.20	7.40	7.20	7.40	7.20	7.40	7.20	7.40	7.20	7.40	7.20	7.40	
P1	4.20	4.40	4.20	4.40	4.20	4.40	4.20	4.40	4.20	4.40	4.20	4.40	
P2	1.95	BSC	3.90	BSC	4.55 BSC		5.85 BSC		7.15 BSC		8.45 BSC		
Х	.30	.50	.30	.50	.30	.50	.30	.50	.30	.50	.30	.50	
е	.65 E	3SC	.65 BSC		.65 BSC		.65 BSC		.65 BSC		.65 E	BSC .	
N	8	3	1	14		16		20		24		28	

TOLERANCES UNLESS SPECIFIED DECIMAL ANGULAR XX± ± XXXX± XXXX±	W W	ID I™	Santa Clo PHONE: (ender Way ara, CA 9: 408) 727- B) 492-86	5054 -6116
	TITLE 4.	PG/PGG PACKAGE (PG OR PA TOPM/ 4 mm BODY WIDTH	ARK COD	E)	PITCH
	SIZE	DRAWING No. PSC—	4056	3	REV 08
	DO NO	OT SCALE DRAWING		SHEET 3	OF S

Ordering Information

Part / Order Number	Marking	Shipping Packaging	Package	Temperature
5V41285PGGI	See Page 10	Tubes	16-pin TSSOP	-40 to +85° C
5V41285PGGI8		Tape and Reel	16-pin TSSOP	-40 to +85° C
5V41285NLGI	See Page 10	Trays	16-pin VFQFPN	-40 to +85° C
5V41285NLGI8		Tape and Reel	16-pin VFQFPN	-40 to +85° C

"G" after the two-letter package code denotes Pb-Free configuration, RoHS compliant.

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Revision History

Rev.	Date	Originator	Description of Change
Α	04/03/12	J. Chao	New datasheet; Preliminary initial release.
В	06/05/12	J. Chao	 Removed references to outputs for Ethernet applications in General Description and Features. Updated pins 1 and 2 in pinout and pin description table from S0:S1 to NC. Removed Output Select table. Removed commercial grade ordering info.
С	06/29/12	J. Chao	 Under output features, changed to "2 - 100MHz 0.7V current mode" Added to the beginning of the CLK1 (pin 10/11) and CLK0 (pin 14/15) descriptions "100MHz HCSL"
D	07/23/12	J. Chao	 Updated Output Features bullet to include "Non-spread" nomenclature. Added "Low Phase Noise:" bullet to Features/Benefits. Added "Output Select Table 1". Updated pin 1 & 2 descriptions to remove NC and replace with S0 and S1 respectively. Updated pin descriptions for pins 1 & 2.
E	07/24/12	J. Chao	Removed 100MHz selection on the pins 10/11 and 14/15 descriptions, and from the Output Features section. Changed Cycle-to-cycle Jitter max. spec from 100ps to 80ps.
F	10/24/12	J. Chao	Added note to page 1 Features/Benefits section stating "For PCIe Gen3 applications, see the 5V41315"
G	06/10/14	J. Chao	Added 16VFQFPN package, tables and all references. Moved to Final.
Н	05/08/17	C.P.	Updated package outline drawings and legal disclaimer.

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